

Description

The XXW4842 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a Battery protection or in other Switching application.



SOP-8

$V_{DS} = 30V$ $I_D = 8A$

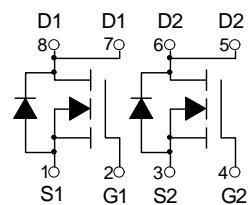
$R_{DS(ON)} < 19m\Omega$ @ $V_{GS}=4.5V$

Application

Battery protection

Load switch

Uninterruptible power supply



Dual N-Channel MOSFET

Absolute Maximum Ratings@ $T_j=25^\circ C$ (unless otherwise specified)

| Symbol | Parameter | Rating | Units |
|----------------------|---|------------|-------|
| V_{DS} | Drain-Source Voltage | 30 | V |
| V_{GS} | Gate-Source Voltage | ± 20 | V |
| $I_D@T_A=25^\circ C$ | Drain Current, $V_{GS} @ 4.5V^3$ | 8 | A |
| $I_D@T_A=70^\circ C$ | Drain Current, $V_{GS} @ 4.5V^3$ | 5.8 | A |
| I_{DM} | Pulsed Drain Current ¹ | 37 | A |
| $P_D@T_A=25^\circ C$ | Total Power Dissipation | 1.5 | W |
| T_{STG} | Storage Temperature Range | -55 to 150 | °C |
| T_J | Operating Junction Temperature Range | -55 to 150 | °C |
| R_{thj-a} | Maximum Thermal Resistance, Junction-ambient ³ | 85 | °C/W |

Electrical Characteristics ($T_J=25^{\circ}\text{C}$, unless otherwise noted)

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|--|--|---|------|-------|-----------|------------------------------|
| BV_{DSS} | Drain-Source Breakdown Voltage | $V_{\text{GS}}=0\text{V}$, $I_{\text{D}}=250\mu\text{A}$ | 30 | --- | --- | V |
| $\Delta \text{BV}_{\text{DSS}}/\Delta T_J$ | BVDSS Temperature Coefficient | Reference to 25°C , $I_{\text{D}}=1\text{mA}$ | --- | 0.034 | --- | $\text{V}/^{\circ}\text{C}$ |
| $R_{\text{DS}(\text{ON})}$ | Static Drain-Source On-Resistance ² | $V_{\text{GS}}=10\text{V}$, $I_{\text{D}}=7\text{A}$ | --- | 17 | 19 | $\text{m}\Omega$ |
| | | $V_{\text{GS}}=4.5\text{V}$, $I_{\text{D}}=4\text{A}$ | --- | 22 | 28 | |
| $V_{\text{GS}(\text{th})}$ | Gate Threshold Voltage | $V_{\text{GS}}=V_{\text{DS}}$, $I_{\text{D}}=250\mu\text{A}$ | 1.2 | --- | 2.5 | V |
| $\Delta V_{\text{GS}(\text{th})}$ | $V_{\text{GS}(\text{th})}$ Temperature Coefficient | | --- | -5.8 | --- | $\text{mV}/^{\circ}\text{C}$ |
| I_{DSS} | Drain-Source Leakage Current | $V_{\text{DS}}=24\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=25^{\circ}\text{C}$ | --- | --- | 1 | uA |
| | | $V_{\text{DS}}=24\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=55^{\circ}\text{C}$ | --- | --- | 5 | |
| I_{GSS} | Gate-Source Leakage Current | $V_{\text{GS}}=\pm 20\text{V}$, $V_{\text{DS}}=0\text{V}$ | --- | --- | ± 100 | nA |
| g_{fs} | Forward Transconductance | $V_{\text{DS}}=5\text{V}$, $I_{\text{D}}=7\text{A}$ | --- | 6 | --- | S |
| R_g | Gate Resistance | $V_{\text{DS}}=0\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$ | --- | 2.5 | --- | Ω |
| Q_g | Total Gate Charge (4.5V) | $V_{\text{DS}}=15\text{V}$, $V_{\text{GS}}=4.5\text{V}$, $I_{\text{D}}=7\text{A}$ | --- | 6 | --- | nC |
| Q_{gs} | Gate-Source Charge | | --- | 2.5 | --- | |
| Q_{gd} | Gate-Drain Charge | | --- | 2.1 | --- | |
| $T_{\text{d}(\text{on})}$ | Turn-On Delay Time | $V_{\text{DD}}=15\text{V}$, $V_{\text{GS}}=10\text{V}$, $R_G=3.3\Omega$ | --- | 2.4 | --- | ns |
| T_r | Rise Time | | --- | 7.8 | --- | |
| $T_{\text{d}(\text{off})}$ | Turn-Off Delay Time | | --- | 22 | --- | |
| T_f | Fall Time | | --- | 4 | --- | |
| C_{iss} | Input Capacitance | $V_{\text{DS}}=15\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$ | --- | 572 | --- | pF |
| C_{oss} | Output Capacitance | | --- | 80 | --- | |
| C_{rss} | Reverse Transfer Capacitance | | --- | 65 | --- | |

Diode Characteristics

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|-----------------|--|--|------|------|------|-------------|
| I_s | Continuous Source Current ^{1,5} | $V_G=V_D=0\text{V}$, Force Current | --- | --- | 7.3 | A |
| I_{SM} | Pulsed Source Current ^{2,5} | | --- | --- | 37 | A |
| V_{SD} | Diode Forward Voltage ² | $V_{\text{GS}}=0\text{V}$, $I_s=1\text{A}$, $T_J=25^{\circ}\text{C}$ | --- | --- | 1.2 | V |
| t_{rr} | Reverse Recovery Time | $I_F=7\text{A}$, $dI/dt=100\text{A}/\mu\text{s}$, $T_J=25^{\circ}\text{C}$ | --- | 20 | --- | nS |
| Q_{rr} | Reverse Recovery Charge | | --- | 1.1 | --- | nC |

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is $V_{\text{DD}}=25\text{V}$, $V_{\text{GS}}=10\text{V}$, $L=0.1\text{mH}$, $I_{\text{AS}}=21\text{A}$
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I_{D} and I_{DM} , in real applications , should be limited by total power dissipation.

Typical Characteristics

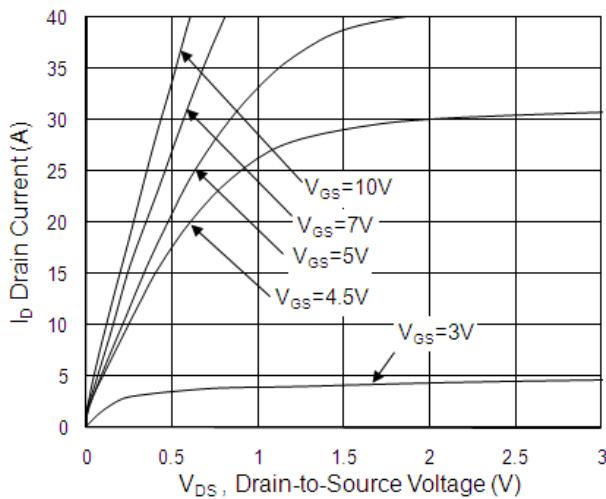


Fig.1 Typical Output Characteristics

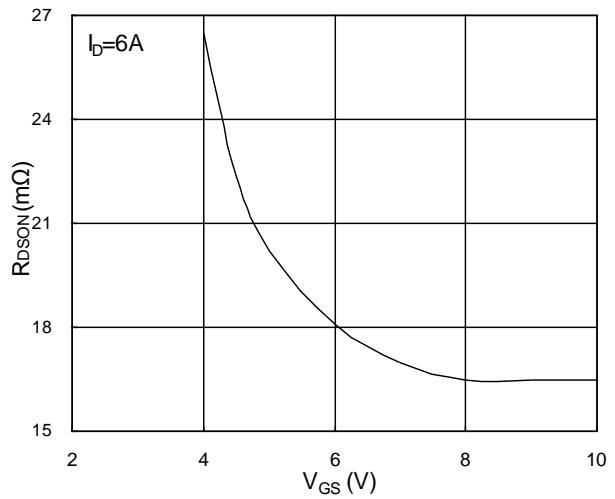


Fig.2 On-Resistance vs. G-S Voltage

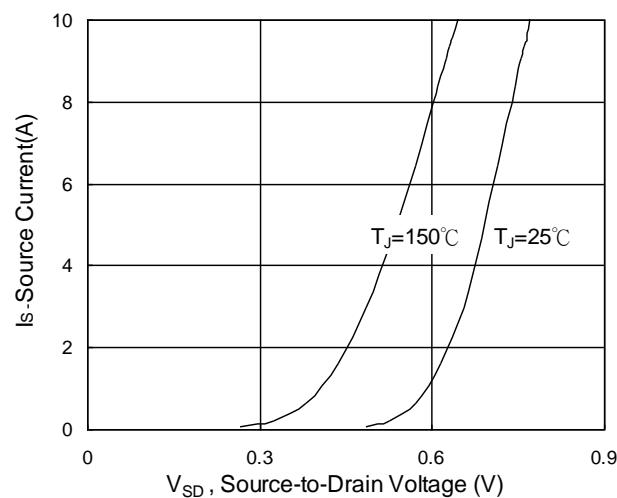


Fig.3 Forward Characteristics Of Reverse

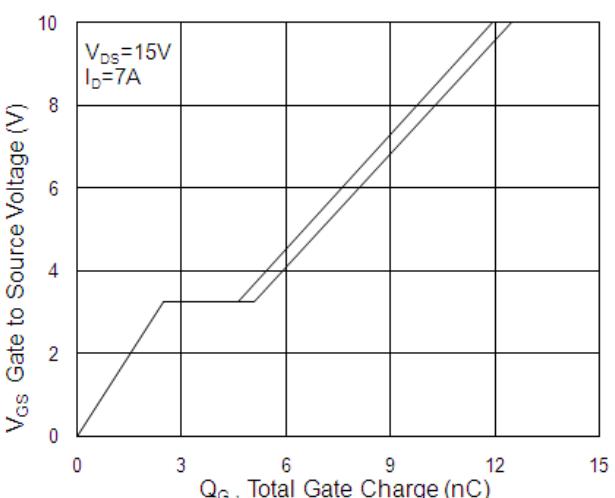


Fig.4 Gate-Charge Characteristics

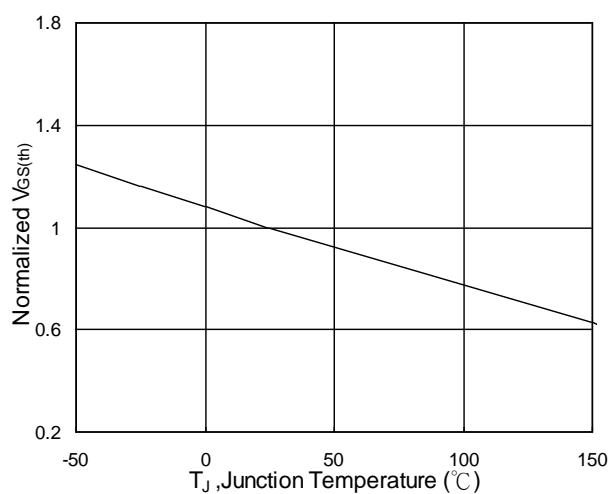


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

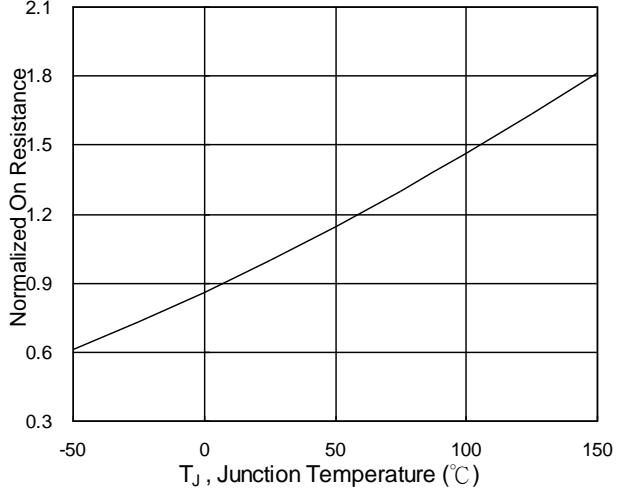
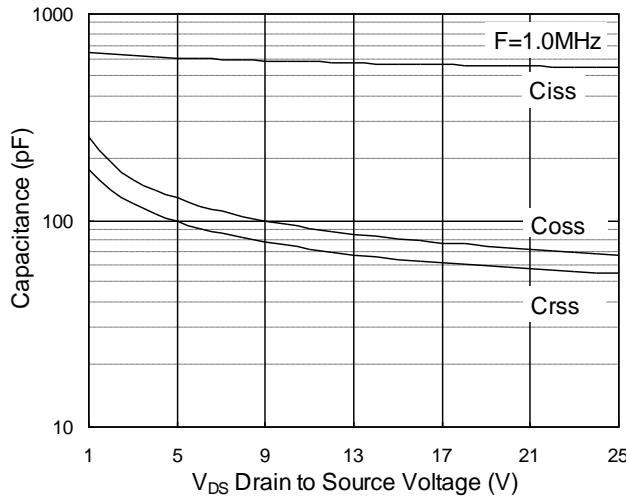
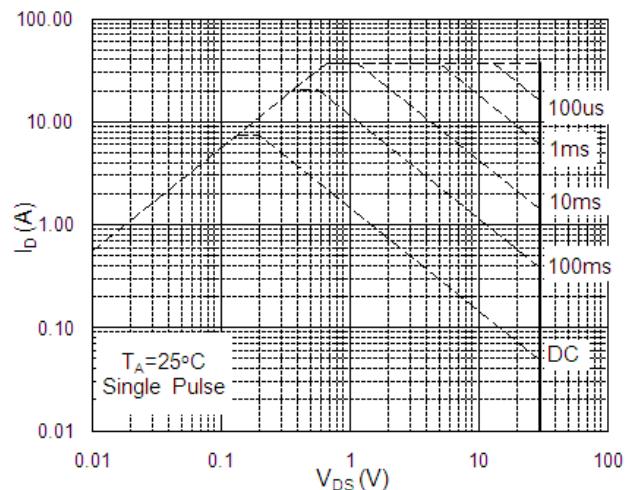
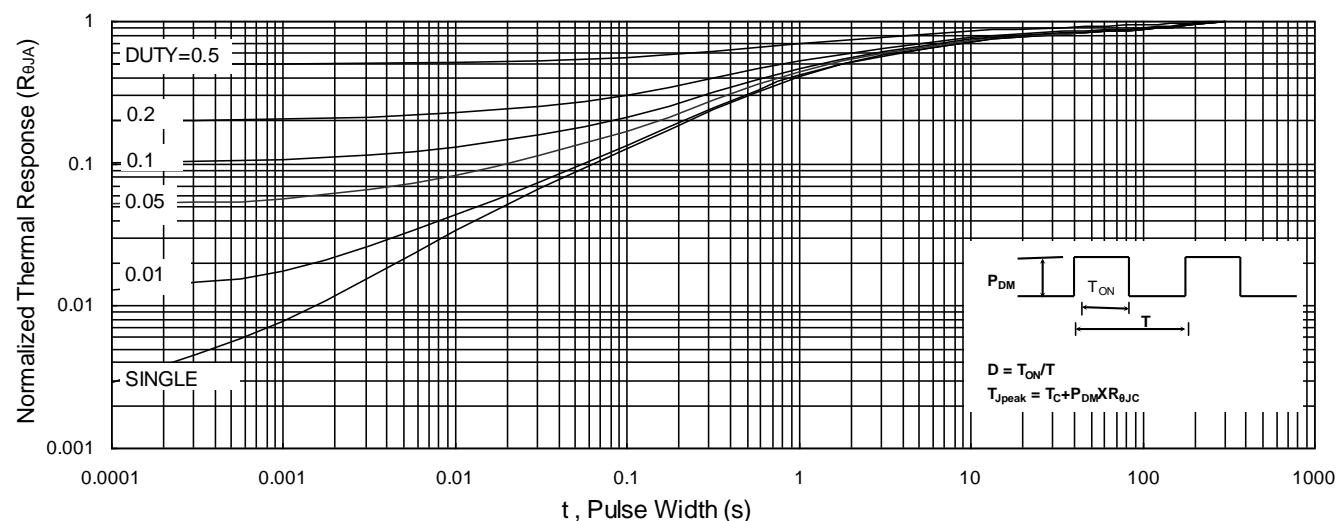
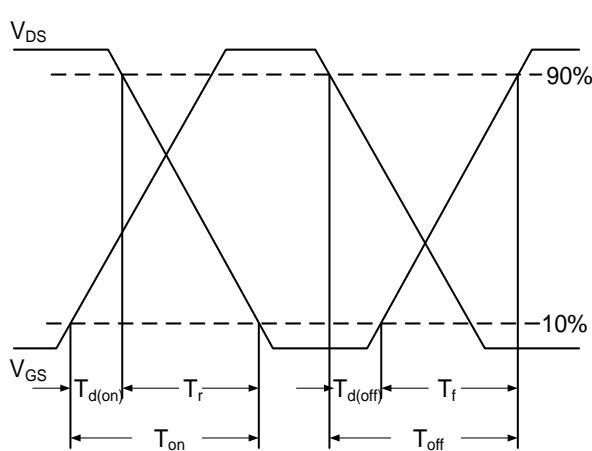
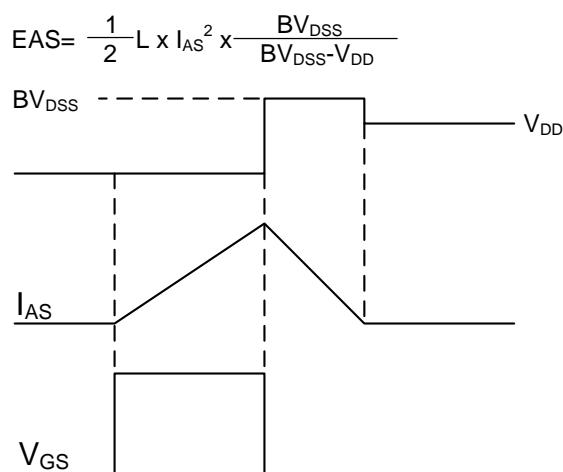
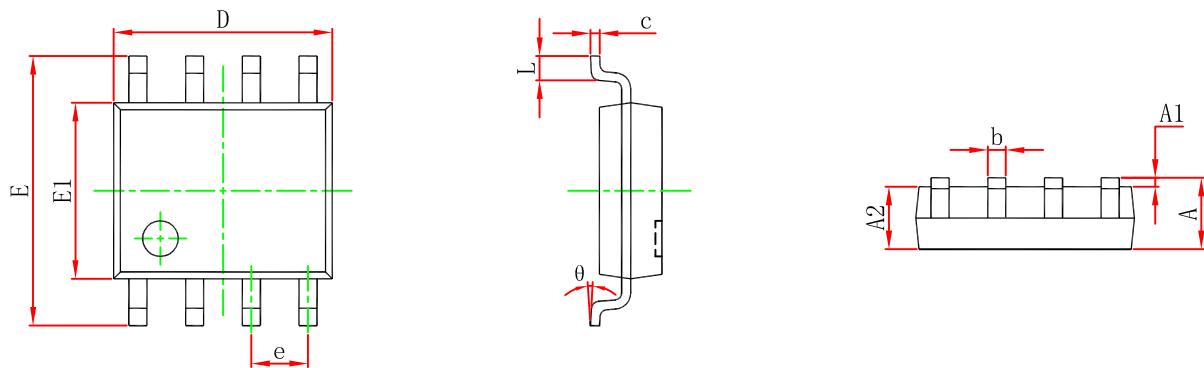


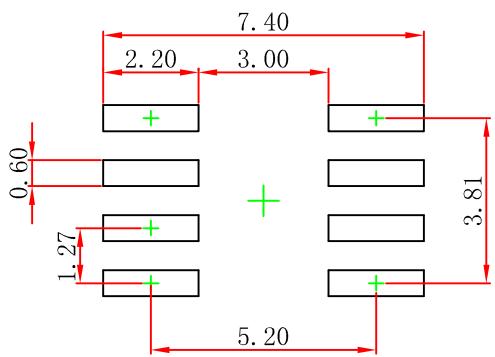
Fig.6 Normalized $R_{DS(on)}$ vs. T_J


Fig.7 Capacitance

Fig.8 Safe Operating Area

Fig.9 Normalized Maximum Transient Thermal Impedance

Fig.10 Switching Time Waveform

Fig.11 Unclamped Inductive Switching Waveform

SOP-8 Package Outline Dimensions



| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|--------|---------------------------|-------|----------------------|-------|
| | Min | Max | Min | Max |
| A | 1.350 | 1.750 | 0.053 | 0.069 |
| A1 | 0.100 | 0.250 | 0.004 | 0.010 |
| A2 | 1.350 | 1.550 | 0.053 | 0.061 |
| b | 0.330 | 0.510 | 0.013 | 0.020 |
| c | 0.170 | 0.250 | 0.007 | 0.010 |
| D | 4.800 | 5.000 | 0.189 | 0.197 |
| e | 1.270 (BSC) | | 0.050 (BSC) | |
| E | 5.800 | 6.200 | 0.228 | 0.244 |
| E1 | 3.800 | 4.000 | 0.150 | 0.157 |
| L | 0.400 | 1.270 | 0.016 | 0.050 |
| θ | 0° | 8° | 0° | 8° |



Note:
 1. Controlling dimension: in millimeters.
 2. General tolerance: $\pm 0.05\text{mm}$.
 3. The pad layout is for reference purposes only.